

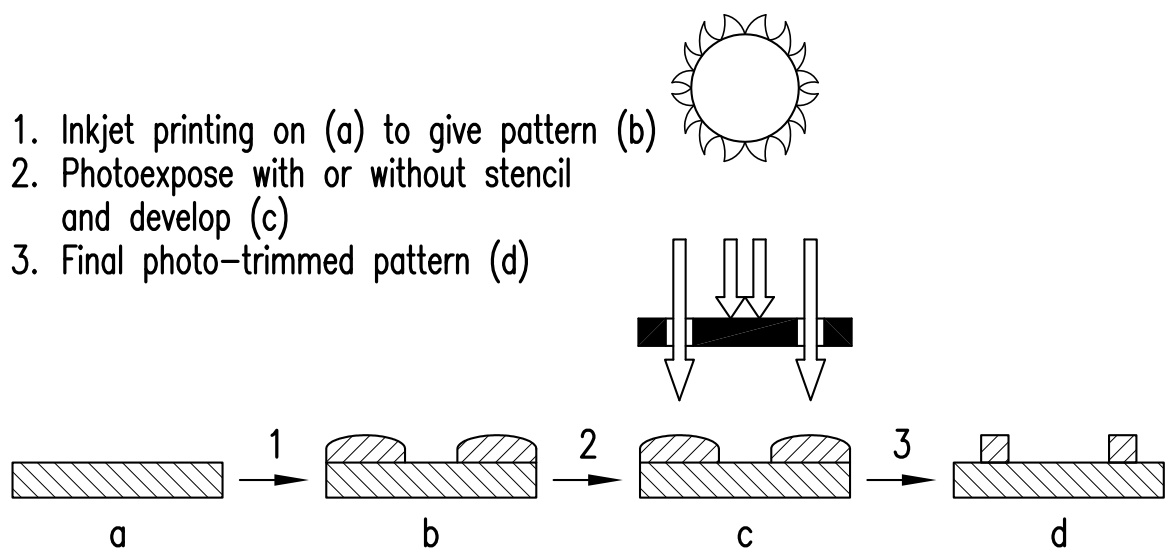


FIG. 1

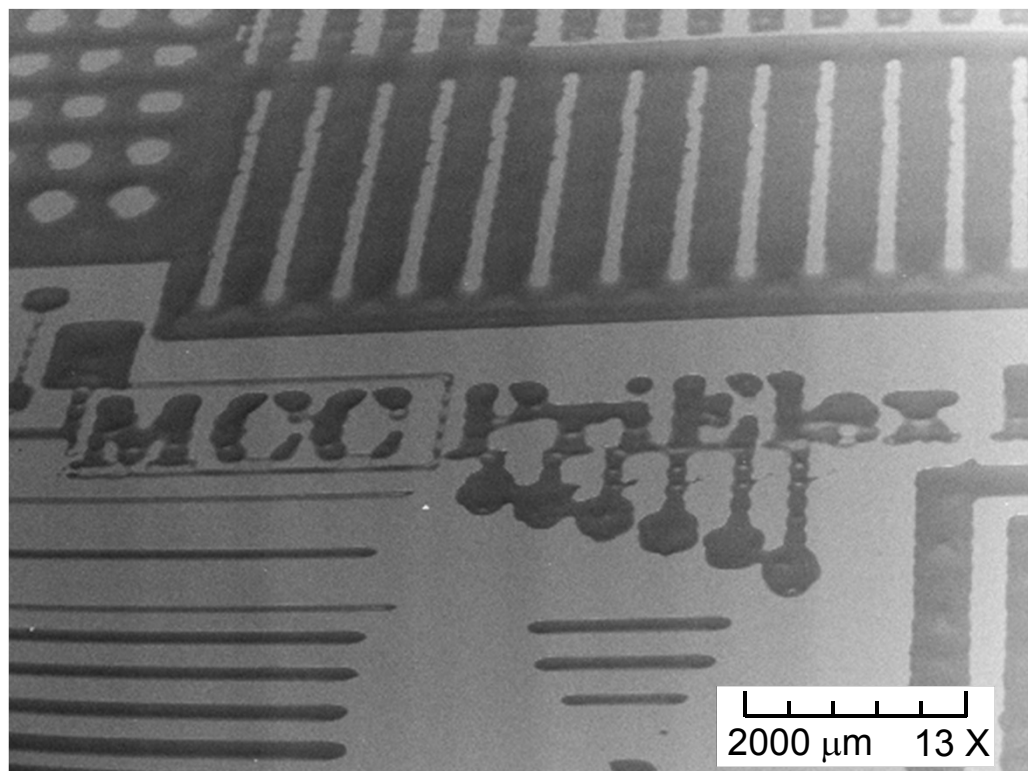


FIG.2

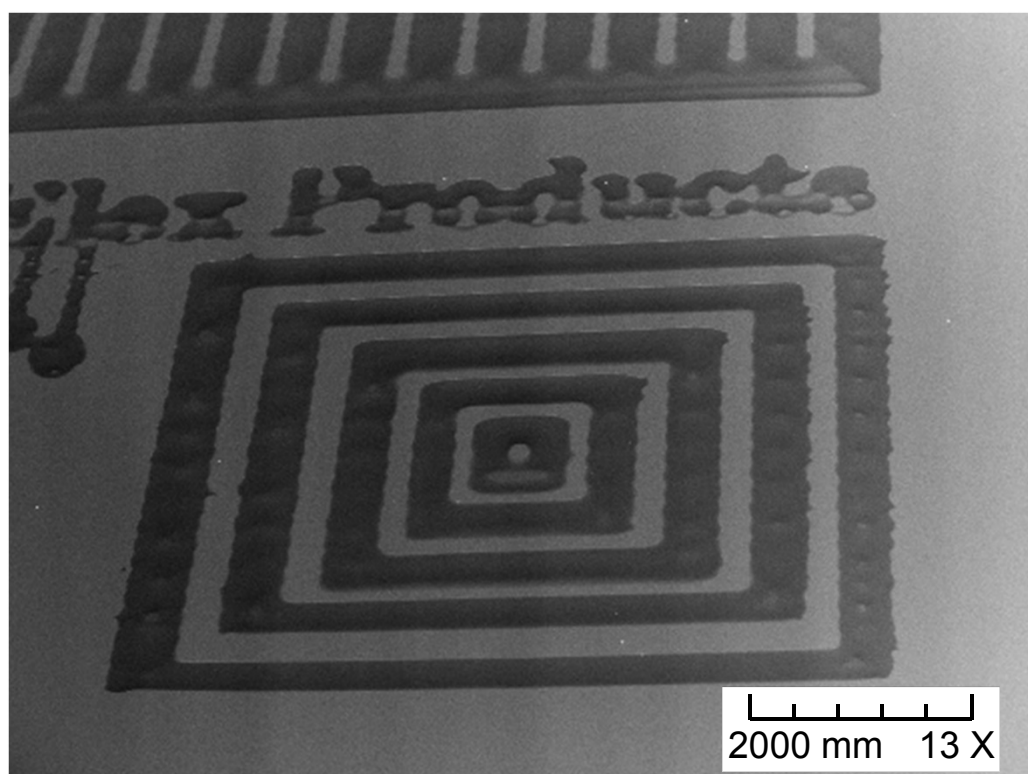


FIG.3

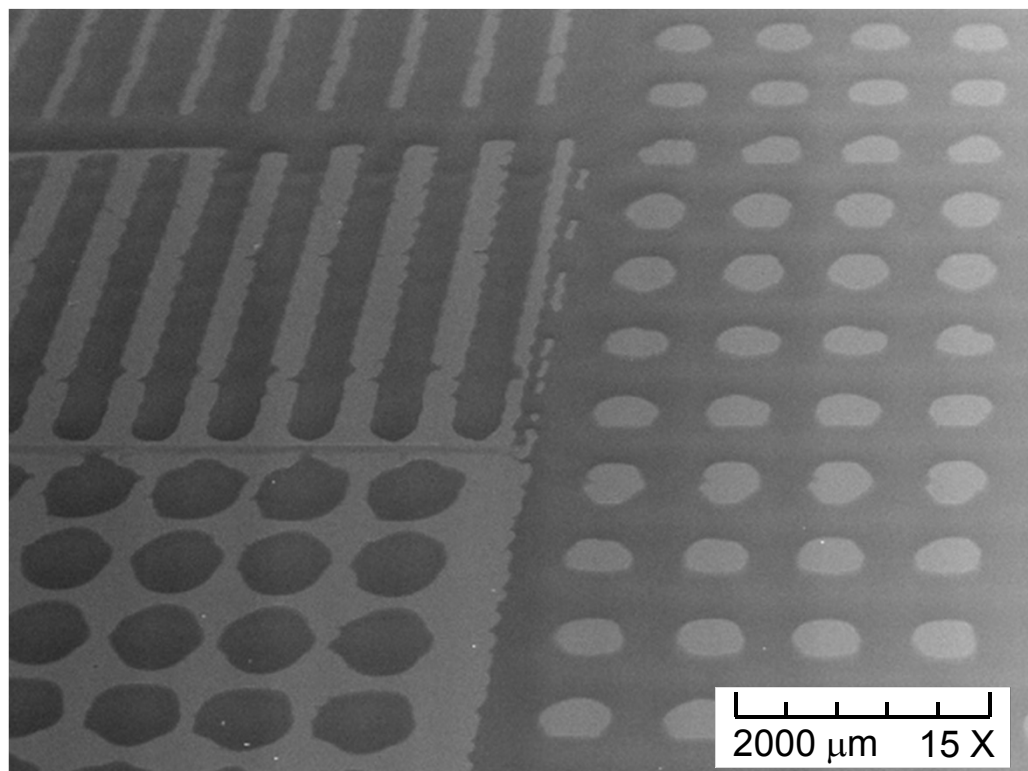


FIG.4

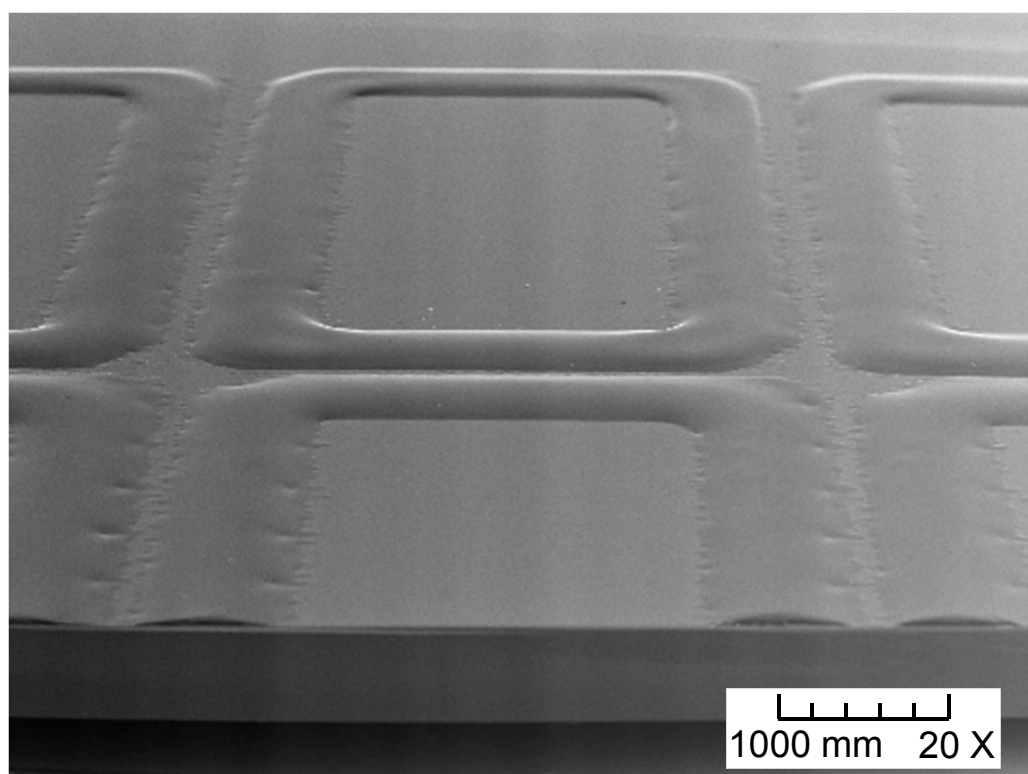


FIG.5

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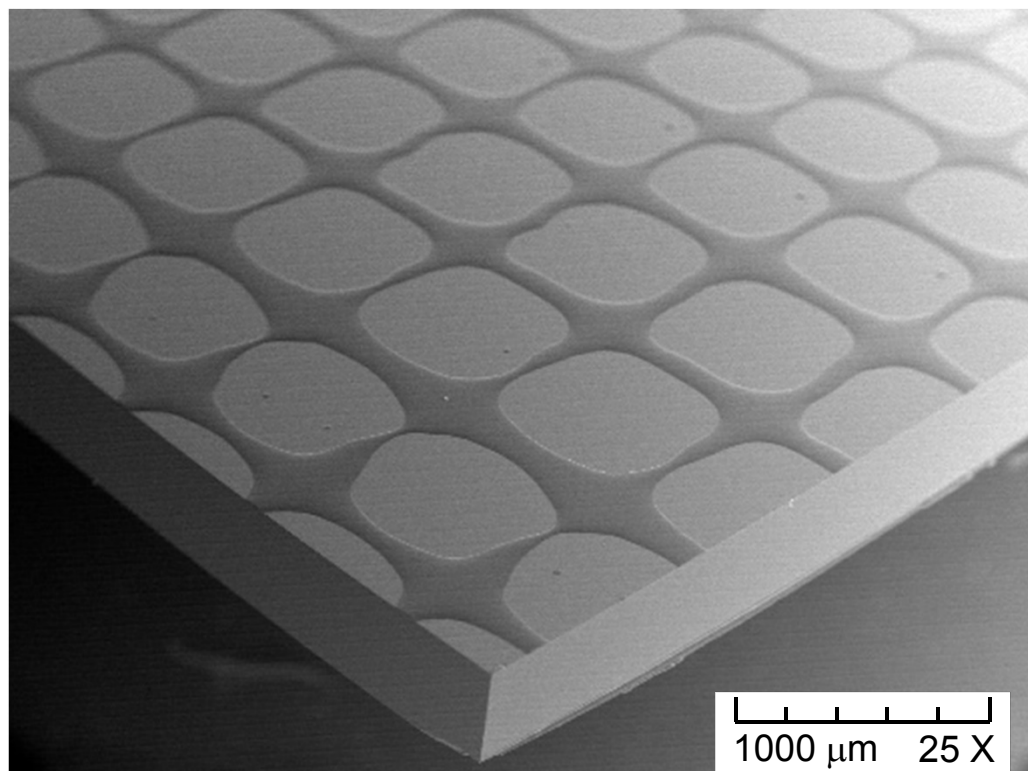


FIG.6

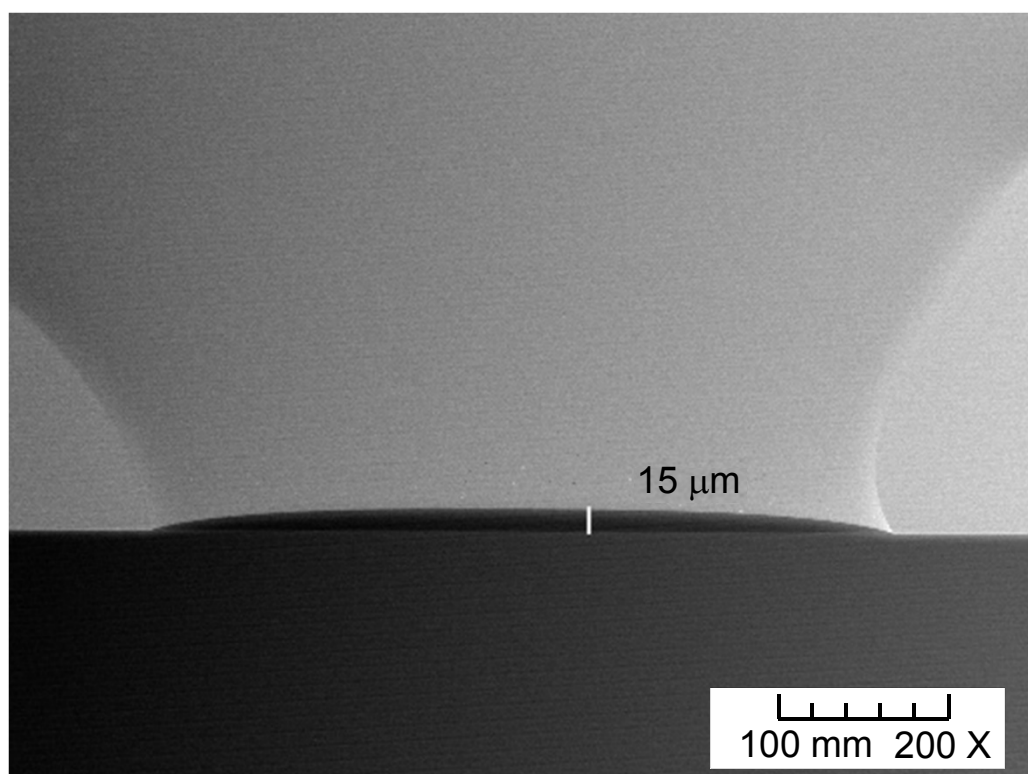


FIG.7

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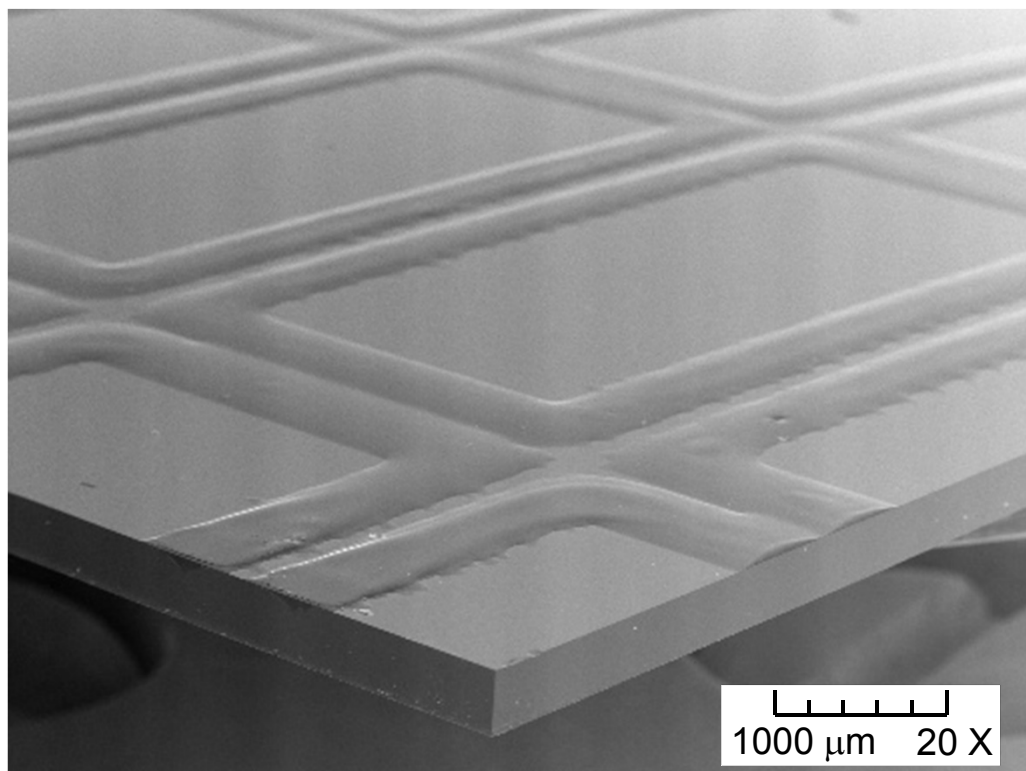


FIG.8

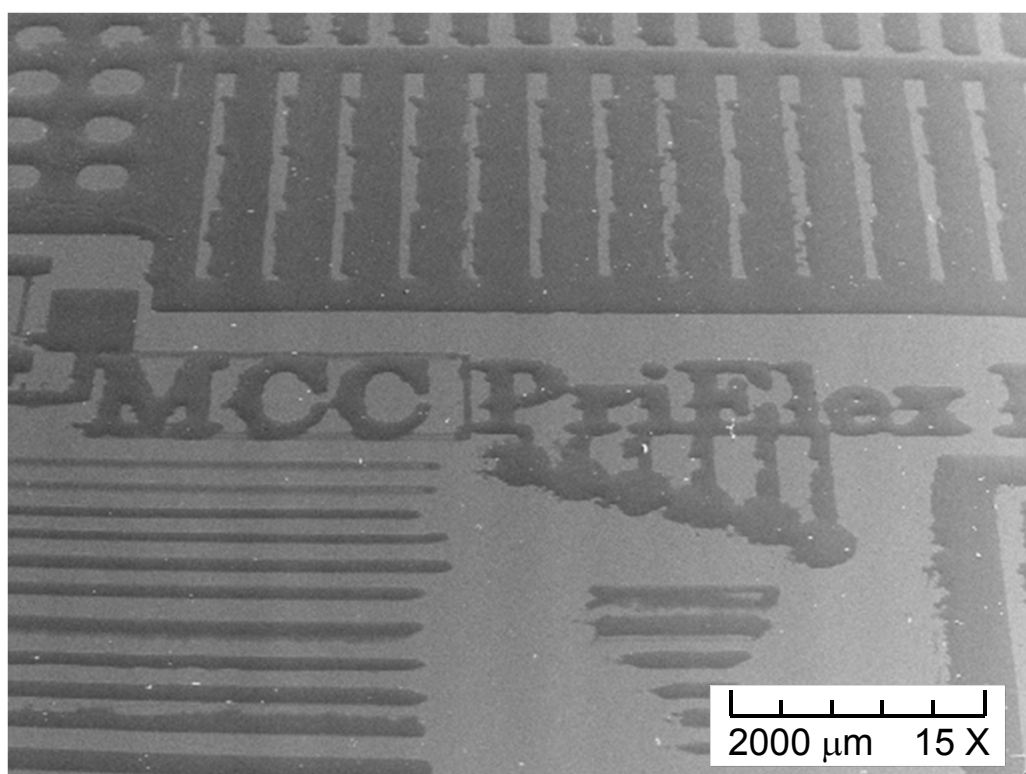


FIG.9

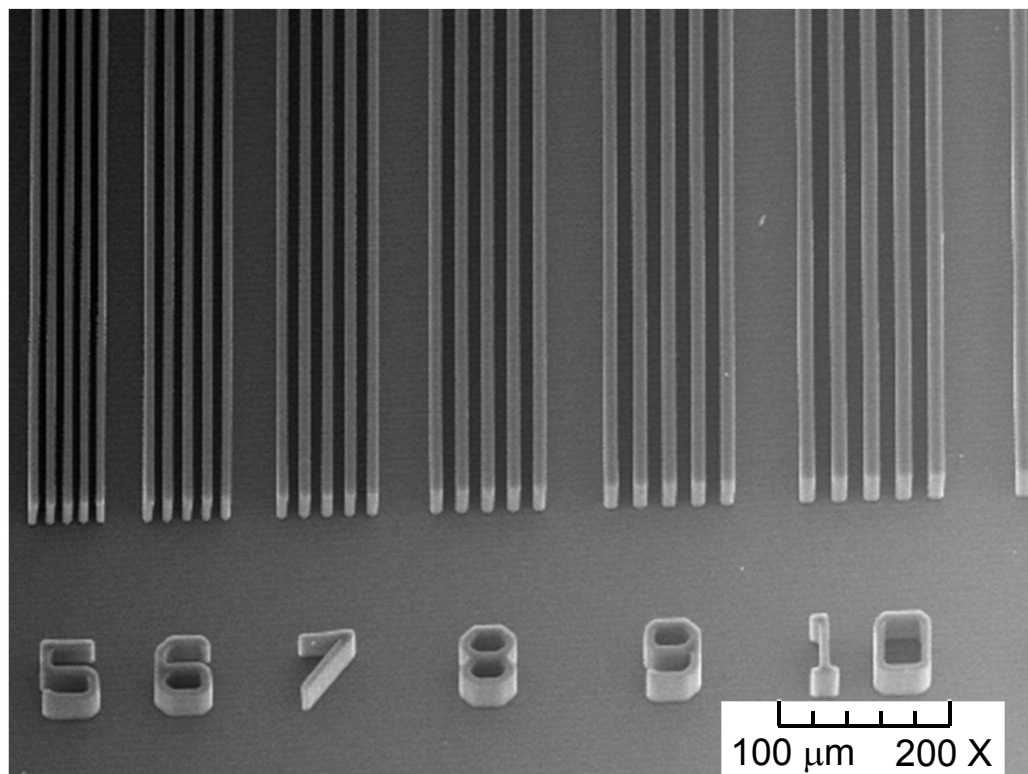


FIG.10

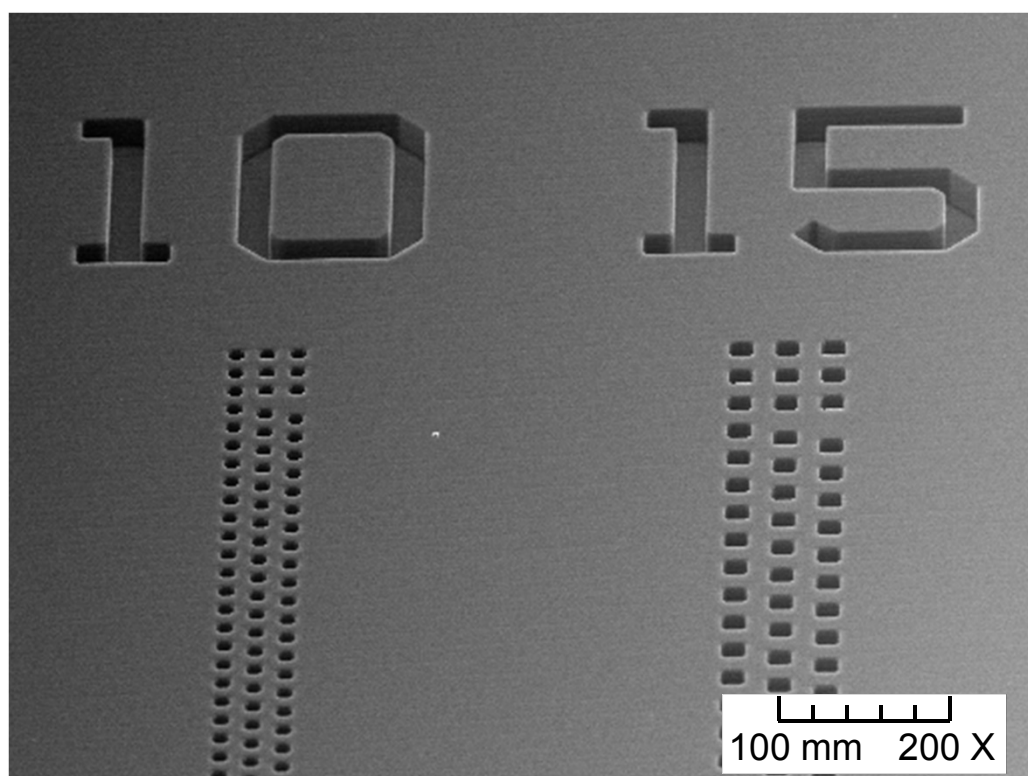


FIG.11

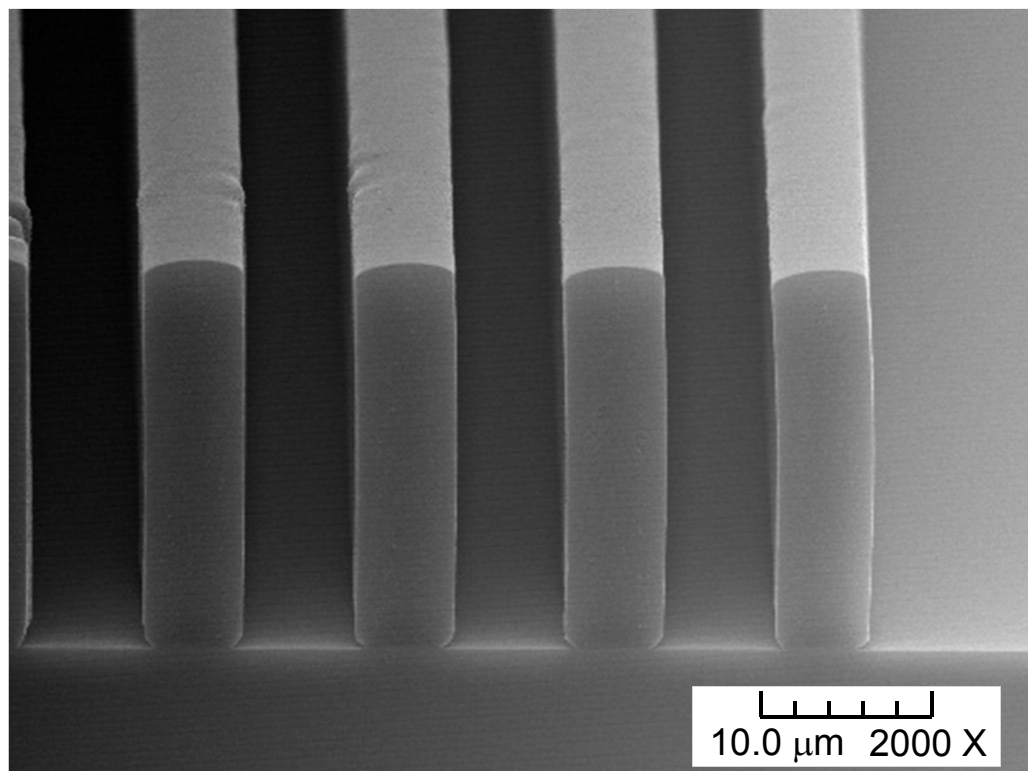


FIG.12

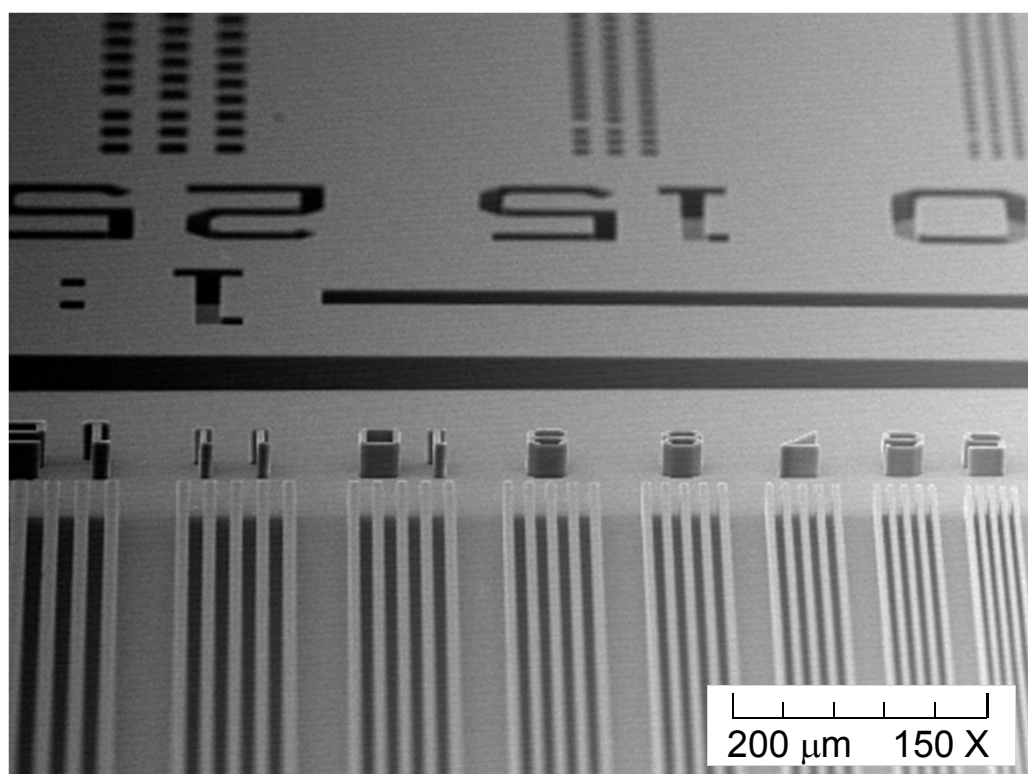


FIG.13

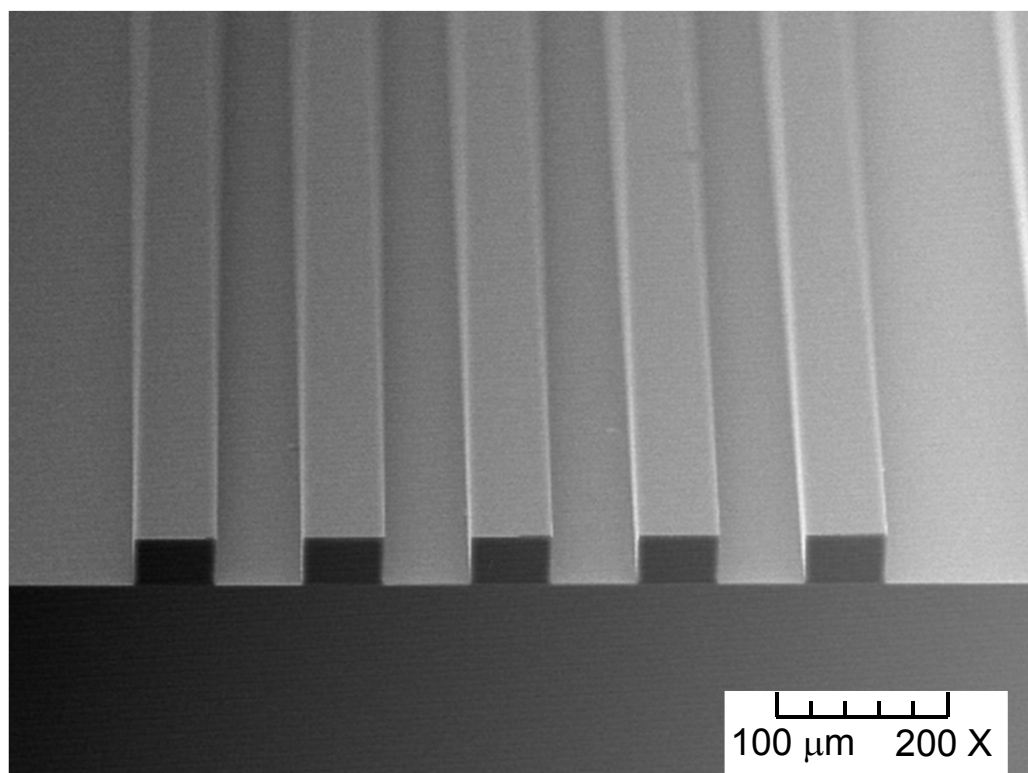


FIG.14

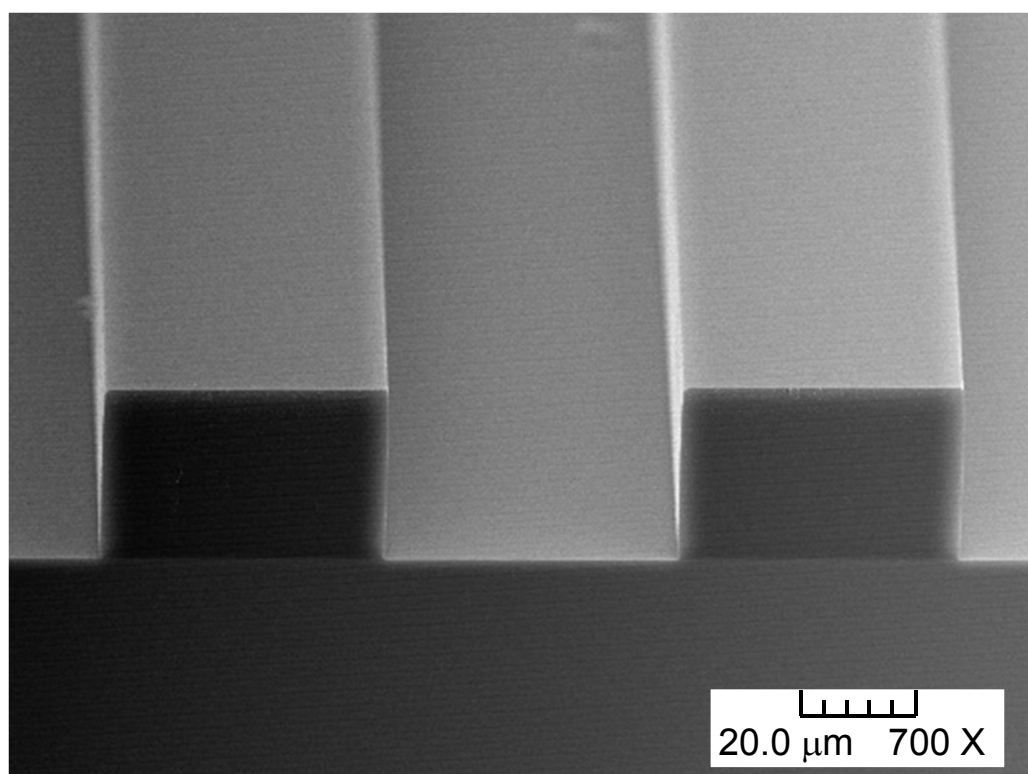
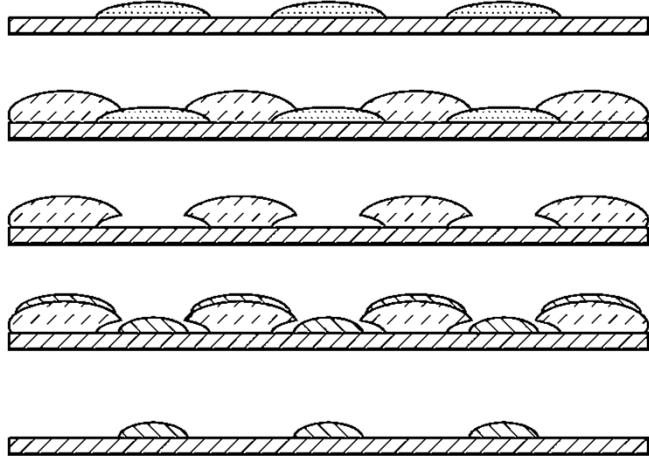


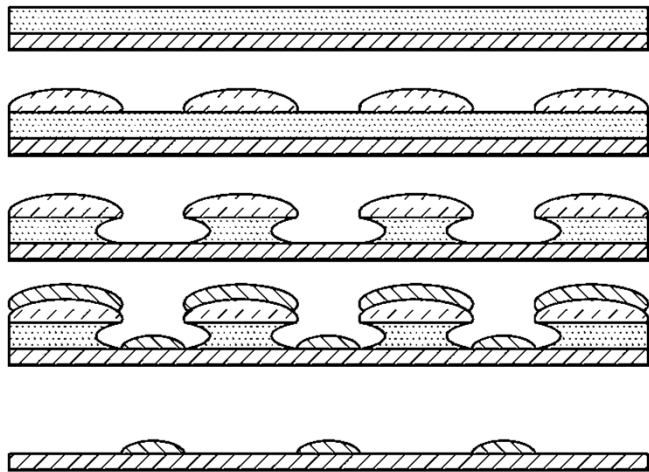
FIG.15

Lift-Off Process, Option 1



1. PMGI ink is deposited
2. UV or thermally cross-linkable ink is deposited.
3. PMGI is dissolved in aqueous base developer.
4. Metal is deposited.
5. Cross-linked ink is removed/lifted-off.

Lift-Off Process, Option 2



1. PMGI ink is deposited
2. UV or thermally cross-linkable ink is deposited.
3. PMGI is dissolved in aqueous developer creating lift-off profile.
4. Metal is deposited.
5. Removal/lifted-off.

Underlayer

PMGI Ink – cure 110 °C for 1 min.

Top Layer

Epoxy Ink – cure 110 °C for 1 min.

Development Time - ~1 min.

2.38% TMAH Developer

FIG.16